

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT(S) : Elliott J. Strauss

TITLE : MODELING METHOD AND
PROGRAM FOR IN-MOLD
COATING AN INJECTION MOLDED
THERMOPLASTIC ARTICLE

APPLICATION NO. : 10/760,992

FILED : January 20, 2004

CONFIRMATION NO. : 1988

EXAMINER : Cuong V. Luu

ART UNIT : 2128

NOTIFICATION OF NON-COMPLIANT : October 29, 2008
APPEAL BRIEF MAILED

ATTORNEY DOCKET NO. : OMNZ 200014

REPLY TO NOTIFICATION OF NON-COMPLIANT APPEAL BRIEF

MAIL STOP APPEAL BRIEF-PATENTS
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

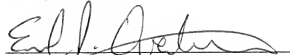
Responsive to the Notification of Non-Compliant Appeal Brief that was mailed October 29, 2008 regarding the above-identified patent application, the Applicant hereby submits page 8 of the Appeal Brief (Grounds of Rejection to be Reviewed on Appeal).

CONCLUSION

The foregoing submission is believed to meet the requirements of the Notification of the Non-Compliant Appeal Brief, and the Applicant awaits further action on the application from the Patent and Trademark Office.

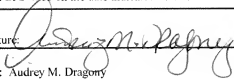
Respectfully submitted,

FAY SHARPE LLP



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November 13, 2008
Date

CERTIFICATE OF MAILING OR TRANSMISSION	
I hereby certify that this correspondence (and any item referred to herein as being attached or enclosed) is (are) being <input type="checkbox"/> deposited with the United States Postal Service as First Class Mail, addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below. <input checked="" type="checkbox"/> transmitted to the USPTO by electronic transmission via EFS-Web on the date indicated below.	
Express Mail Label No.:	Signature: 
Date: November 13, 2008	Name: Audrey M. Dragony

VI. GROUNDS OF REJECTION TO BE REVIEWED ON APPEAL

The following grounds of rejection are presented for review:

Claims 20 and 27-28 are rejected under 35 U.S.C. §102(b) as being anticipated by Chen et al (In Mold Functional Coating of Thermoplastic Substrate: Process Modeling, Antec 2001, 255).

Claims 11-14 and 17-18 are rejected under 35 U.S.C. §103(a) as being unpatentable over Chen et al. in view of Ladeinde (A Procedure for Advection and Diffusion in Thin Cavities, Computational Mechanics 15 (1995) pp. 511-520, Springer-Verlag, 1995).

Claims 15-16 are rejected under 35 U.S.C. §103(a) as being unpatentable over Chen in view of Ladeinde as applied to claim 13 above, and further in view of Walsh (U.S. Patent 6,099,162).

Claim 21 is rejected under 35 U.S.C. §103(a) as being unpatentable over Chen as applied to claim 20 and further in view of Ladeinde.

Claims 22-24 are rejected under 35 U.S.C. §103(a) as being unpatentable over Chen as applied to claim 20 and further in view of Zuyev (Optimizing Injection Gate Location and Cycle Time for the In-Mold Coating (IMC) Process, Antec 2001).

Claims 25-26 are rejected under 35 U.S.C. §103(a) as being unpatentable over Chen in view of Zuyev as applied to claim 23 above, and further in view of Walsh (U.S. Patent 6,099,162).